

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6938664

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JUNG HO RYU	09/09/2021
SONY AKKARAKARAN	08/27/2021
TAO LUO	08/27/2021
JUNYI LI	08/27/2021
TIANYANG BAI	09/07/2021
XIAOJIE WANG	08/30/2021
XIAOXIA ZHANG	09/05/2021
JING SUN	08/27/2021
PETER GAAL	08/27/2021
JUAN MONTOJO	08/29/2021
PIYUSH GUPTA	09/10/2021
WOOSEOK NAM	08/27/2021
MAHMOUD TAHERZADEH BOROUJENI	09/25/2021
HUA WANG	08/29/2021
LIK HANG SILAS FONG	09/01/2021
YAN ZHOU	08/29/2021

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17404828

CORRESPONDENCE DATA

Fax Number: (619)235-0398

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

PATENT

Phone: 619-238-1900
Email: Docketing@procopio.com, Patrick.Lemus@procopio.com
Correspondent Name: PROCOPIO CORY HARGREAVES & SAVITCH LLP
Address Line 1: 525 B STREET, SUITE 2200
Address Line 4: SAN DIEGO, CALIFORNIA 92101

ATTORNEY DOCKET NUMBER: 129025-0914TU01/2104526

NAME OF SUBMITTER: PATRICK LEMUS

SIGNATURE: /Patrick Lemus/

DATE SIGNED: 09/27/2021

Total Attachments: 19

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ASSIGNMENT

WHEREAS, WE,

1. **Jung Ho RYU**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
2. **Sony AKKARAKARAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
3. **Tao LUO**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
4. **Junyi LI**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
5. **Tianyang BAI**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
6. **Xiaojie WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
7. **Xiaoxia ZHANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
8. **Jing SUN**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
9. **Peter GAAL**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
10. **Juan MONTOJO**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
11. **Piyush GUPTA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
12. **Woosok NAM**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
13. **Mahmoud TAHERZADEH BOROUJENI**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
14. **Hua WANG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
15. **Lik Hang Silas FONG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
16. **Yan ZHOU**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **TECHNIQUES TO FACILITATE PHASE JUMP ESTIMATION FOR SIDELINK DMRS BUNDLING** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

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WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s). 17/404,828** filed **August 17, 2021, Qualcomm Reference Number 2104526**, and all provisional applications relating thereto (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number (s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

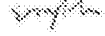
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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at FL Lee, NJ, USA on 9/19/21 Jung Ho RYU
City, State, Country Date Jung Ho RYU

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Poway, CA, USA, on 8/27/2021 
City, State, Country Date Sony AKKARAKARAN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done
at

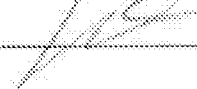
Sandieg CA
City, State, Country

on

08/27/2021
Date

[Signature]
Tao LUO

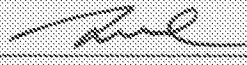
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Bridgewater, NJ, USA on 8/27/2011 
City, State, Country Date Junyi Li

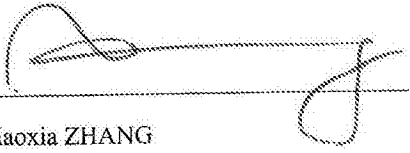
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Somerville, MA, USA on 09/07/2024 Tianyang Bai
City, State, Country Date Tianyang Bai

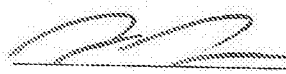
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hillsborough, NJ, US on 08/30/2021 
City, State, Country Date Xiaojie WANG

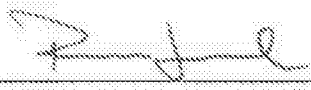
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, U.S. on 09/05/2021 
City, State, Country Date Xiaoxia ZHANG

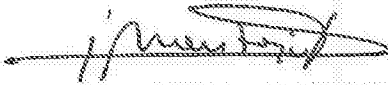
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, USA on 8/27/21 
City, State, Country Date Jing SUN


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, U.S.A. on 08/27/2021 
City, State, Country Date Peter GAAL


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, USA on 8/29/21 
City, State, Country Date Juan MONTOJO

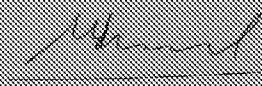
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Bridgewater, NJ on Sep 19, '21 
City, State, Country Date Piyush GUPTA


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, USA on 8/27/2021 
City, State, Country Date Wooseok NAM

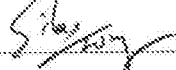
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Date San Diego, CA, USA on Sep 25, 2021 
at City, State, Country Date Mahmoud TAHERZADEH BOROUJENI


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Dublin, OH, USA on 08/29/2024 
City, State, Country Date Hua WANG

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Bridgewater, NJ, USA on 9/1/2021 
City, State, Country Date Lik Hang Silas FONG

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, US on 08/29/2021 
City, State, Country Date Yan ZHOU